
Tehnologija površinske montaže - 4. del: Razvrščanje, pakiranje, etiketiranje in ravnanje z napravami, občutljivimi na vlago

Surface mounting technology - Part 4: Classification, packaging, labelling and handling of moisture sensitive devices

Oberflächenmontagetechnik - Teil 4: Genormtes Verfahren zur Klassifikation, Verpackung, Kennzeichnung und Handhabung feuchteempfindlicher Bauteile

Technique du montage en surface - Partie 4: Classification, emballage, étiquetage et manipulation des dispositifs sensibles à l'humidité

Ta slovenski standard je istoveten z: prEN IEC 61760-4:2025

[oSIST prEN IEC 61760-4:2025](https://standards.sist.si/standards/sist/61760-4/2025/prEN-IEC-61760-4-2025)

ICS:

31.190

Sestavljeni elektronski
elementi

Electronic component
assemblies

oSIST prEN IEC 61760-4:2025

en



91/2039/CDV

COMMITTEE DRAFT FOR VOTE (CDV)

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SECRETARIAT:

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SECRETARY:

Mr Osamu IKEDA

OF INTEREST TO THE FOLLOWING COMMITTEES:

TC 40, TC 47, TC 86

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☒ SUBMITTED FOR CENELEC PARALLEL VOTING☐ NOT SUBMITTED FOR CENELEC PARALLEL VOTING**Attention IEC-CENELEC parallel voting**

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TITLE:

Surface mounting technology - Part 4: Classification, packaging, labelling and handling of moisture sensitive devices

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